

# SOT865-2

plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 7 x 7 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN32
<b>Package type industry code</b>	HVQFN32
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-3-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.8	-	0.85	0.9	mm
A <sub>2</sub>	package height	0.6	-	0.62	0.7	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	



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## 2. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 7 x 7 x 0.85 mm

SOT865-2

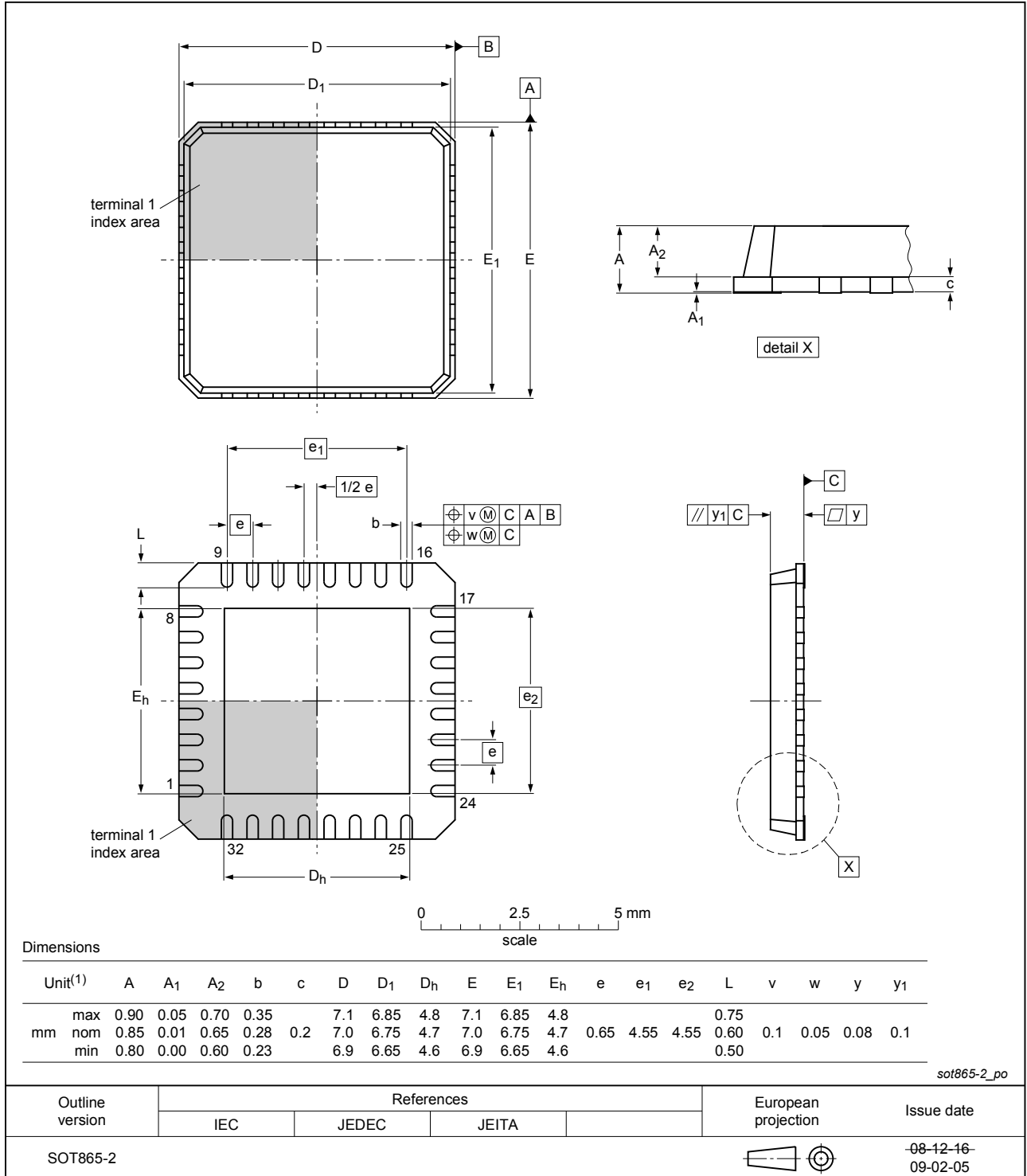


Fig. 1. Package outline HVQFN32 (SOT865-2)

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### 3. Soldering

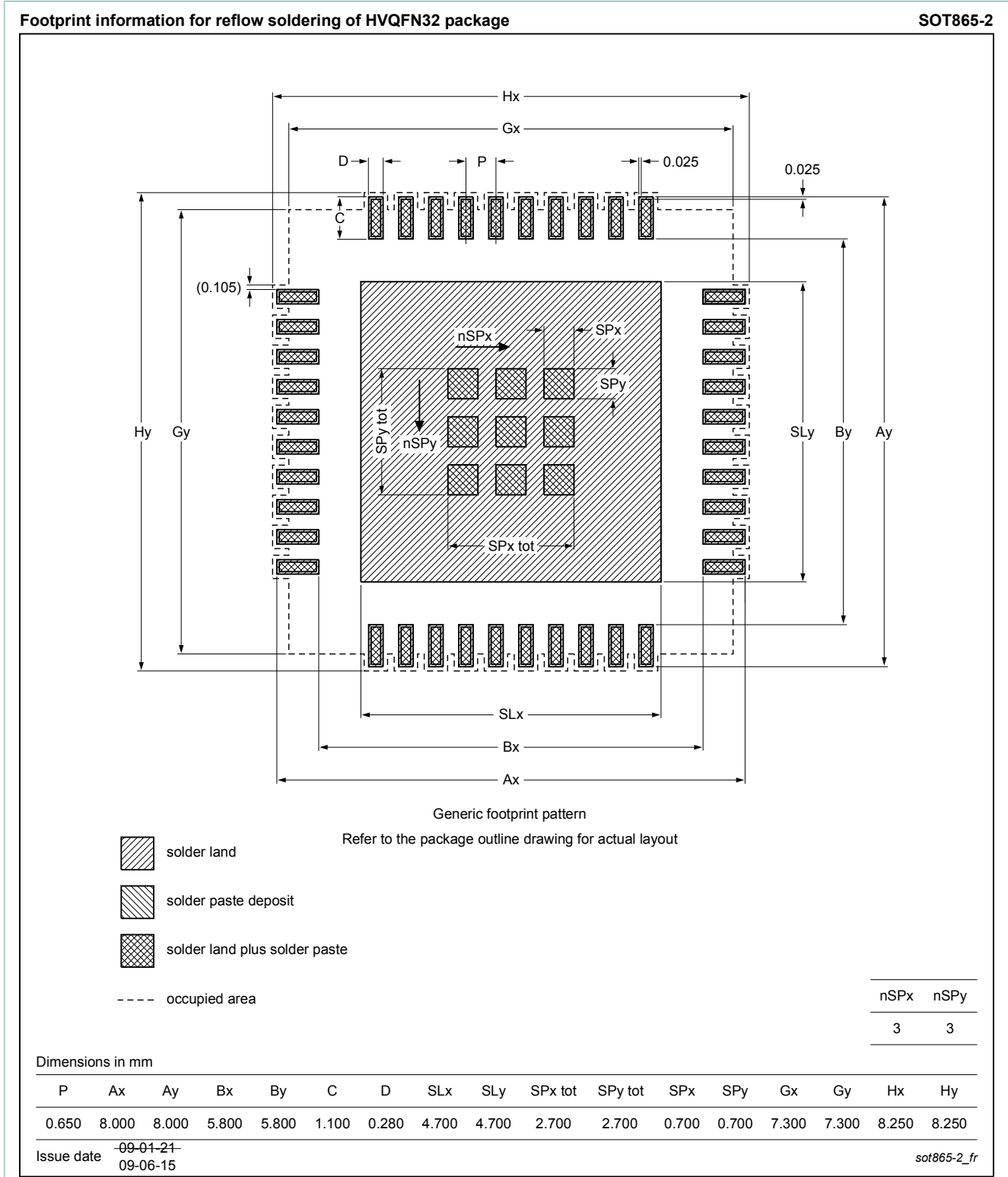


Fig. 2. Reflow soldering footprint for HVQFN32 (SOT865-2)

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## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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